THICK PRINT COPPER PASTES FOR ALUMINUM NITRIDE SUBSTRATES

Abstract

The invention provides an electroconductive paste comprising 50–90 wt. % of copper particle, 0.5–10 wt. % of a glass frit, 0.1–5% wt. % of adhesion promoter, which is at least one selected member from the group consisting of cuprous oxide, titanium oxide, zirconium oxide, boron resinate, zirconium resinate, amorphous boron, lithium phosphate, bismuth oxide, aluminum oxide, and zinc oxide, and 5–20 wt. % of an organic vehicle. An article comprising an aluminum nitride substrate and electroconductive paste of the invention is also provided. A method of forming an electroconductive circuit comprising is also provided.

Fig. 1